

MA4L784

Silicon epitaxial planar type

For high speed switching

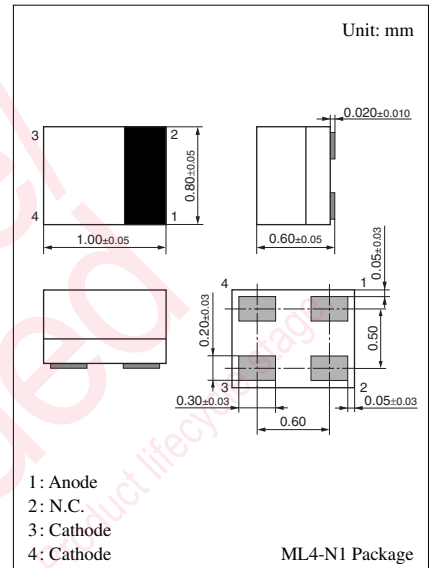
For small current rectification

■ Features

- High-density mounting is possible
- Optimum for high frequency rectification because of its short reverse recovery time (t_{rr})
- Low forward voltage V_F and good rectification efficiency
- 1008-type mold leadless 4-pin package

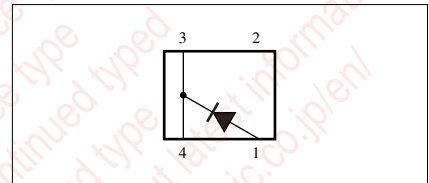
■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage (DC)	V_R	30	V
Peak reverse voltage	V_{RM}	30	V
Forward current (DC)	I_F	100	mA
Peak forward current	I_{FM}	300	mA
Junction temperature	T_j	125	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +125	$^\circ\text{C}$



Marking Symbol: Y

Internal Connection



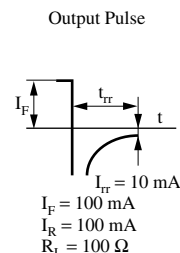
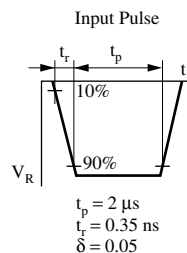
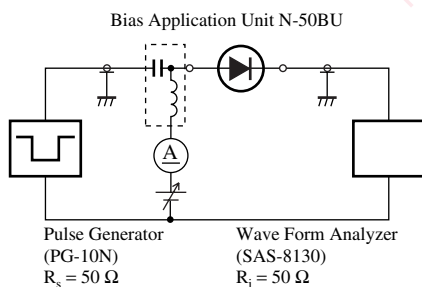
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

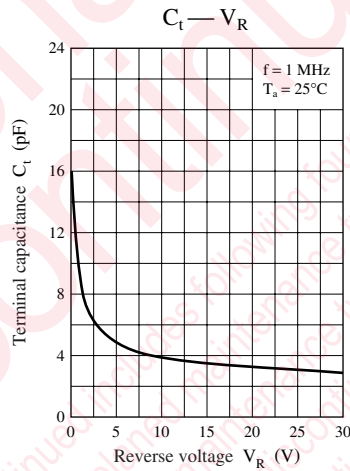
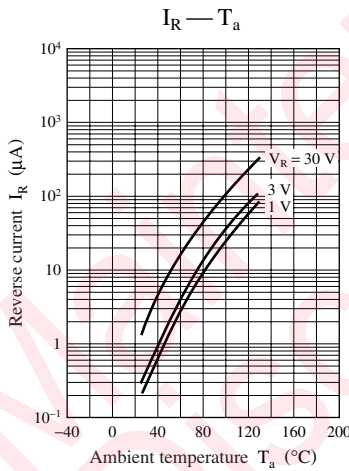
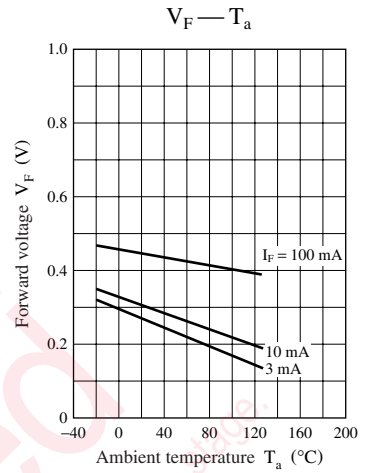
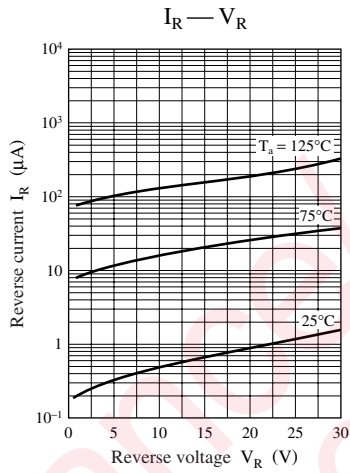
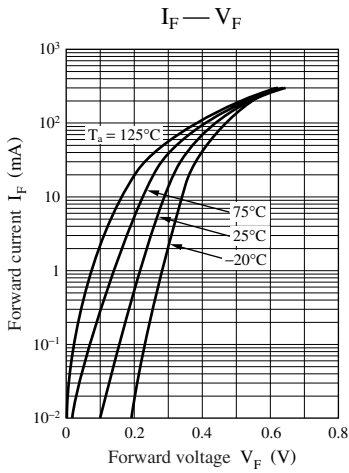
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse current (DC)	I_R	$V_R = 30\text{ V}$			15	μA
Forward voltage (DC)	V_F	$I_F = 100\text{ mA}$			0.55	V
Terminal capacitance	C_t	$V_R = 0\text{ V}, f = 1\text{ MHz}$		20		pF
Reverse recovery time *	t_{rr}	$I_F = I_R = 100\text{ mA}$ $I_{tr} = 10\text{ mA}, R_L = 100\ \Omega$		2.0		ns

Note) 1. This product is sensitive to electric shock (static electricity, etc.).

Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

2. Rated input/output frequency: 2 GHz
3. *: t_{rr} measuring instrument





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